IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					als and Mfg Information				
upplier Info												<u> </u>			
Company name* Comp				ompany unique ID			Unique ID Authority				Response Date*				
nsemi										2024-05-04					
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*					
Product-Env-Ste	ewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Compliance				ro Compliance			NA					Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Versio	on	Manufacturing Site		Weight*	UOM	Unit Type	
		AR0233 A1-DRB		2MP 1/3 CIS SO			2024-05-04			TA1	2	245.7	mg	Each	
Ianufacturin	ng Proccess Informat	ion													
Terminal Plating / Grid Array Material Terminal Ba			erminal Base A	Alloy	J-STD-020 MS	ISL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle					eles				
SnAgCu		U Alloy 3			260 C 30		30	seconds 3							
omments															
TENTION: M	ISL 3 Rated item requires	Bake and D	ry Pack (after	electrical test)											
or more inform	ation regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	51.92	mg		Misc.	proprietary data		0.1973	mg
			Supplier	Silicon (Si)	7440-21-3		51.2087	mg
			Supplier	Aluminum (Al)	7429-90-5		0.514	mg
Die Attach	3.16	mg		Bismaleimide Monomer	proprietary data		1.2166	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0158	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.316	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0158	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.316	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.316	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0158	mg
			Supplier	Other Additive Agents	Proprietary Data		0.632	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.316	mg
Epoxy	1.6	mg	Supplier	Imidazole Addition	68490-66-4		0.48	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.16	mg
			Supplier	Zirconium Dioxide (ZrO2)	1314-23-4		0.16	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.16	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.64	mg
Imaging Lens	35.37	mg	Supplier	Sulfur (S)	7704-34-9		0.1768	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.7685	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.7685	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		1.7685	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.7685	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.7685	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.7685	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		24.5821	mg
Mold Compound	71.19	mg	Supplier	Triphenylphosphine	603-35-0		0.3559	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.3559	mg
			Supplier	Oxirane	39817-09-9		14.238	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		14.238	mg

			Supplier	Misc.	Proprietary Data	3.5595	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	34.8831	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	3.5595	mg
Solder Ball	37.75	mg	Supplier	Silver (Ag)	7440-22-4	1.1325	mg
			Supplier	Tin (Sn)	7440-31-5	36.4287	mg
			Supplier	Copper (Cu)	7440-50-8	0.1887	mg
Solder Mask	4.77	mg		Epoxy resin	proprietary data	0.5724	mg
			Supplier	Acrylate	Proprietary Data	1.8221	mg
			Supplier	Talc	14807-96-6	0.1288	mg
			Supplier	Miscellaneous	Trade Secret	0.1765	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	2.0702	mg
Substrate Copper Foil	3.68	mg	Supplier	Copper (Cu)	7440-50-8	3.68	mg
Substrate - Core Material	18.25	mg		Epoxy resin	proprietary data	10.585	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	7.665	mg
Substrate Plating-Au	0.31	mg	Supplier	Gold (Au)	7440-57-5	0.31	mg
Substrate Plating-Cu	16.42	mg	Supplier	Copper (Cu)	7440-50-8	16.42	mg
Substrate Plating-Ni	0.76	mg	В	Nickel (Ni)	7440-02-0	0.76	mg
Wire Bond - Au	0.52	mg	Supplier	Gold (Au)	7440-57-5	0.52	mg